



IFW

PATENT

Docket No. JCLA10543

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IN THE UNITED STATE PATENT AND TRADEMARK OFFICE

In re Application of : TSUNG-MING PAI et al.

Application No. : 10/789,171

Filed : February 26,2004

For **FLIP-CHIP PACKAGE AND
: FABRICATING PROCESS THEREOF**

Certificate of Mailing

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July 19, 2004

(Date)


Jiawei Huang, Reg. No. 43,330

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith is a certified copy of **Taiwan** Application No. **92104000** filed on **February 26, 2003**.

A return prepaid postcard is also included herewith.

It is believed no fee is due. However, the Commissioner is authorized to charge any fees required, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 50-0710 (Order No. JCLA10543).

Date: 7/19/2004

By: 
Jiawei Huang
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